

----- CALL FOR ABSTRACTS -----



IMAPS 2019 Technical Track on:

Wafer Level/Panel Level (Advanced RDL)

Track Co-Chair:	Track Co-Chair:
Rey Alvarado, Qualcomm reya@qti.qualcomm.com	Beth Keser, Intel beth.keser@intel.com

The objective of this Technical Track is to have a unique forum that brings together scientists, engineers, manufacturers, academia, and business people from around the world who have been working in the area of Wafer Level Packaging (WLP), Fan-Out Wafer Level Packaging (FO-WLP), and Panel Level Packaging (PLP). Topics addressed in this track include WLP and FO-WLP advanced structures, process, and reliability including new materials and equipment for both 300mm and panel level. Advanced redistribution layers (RDL) is also included to address the drive to increase routing density and produce sub 2 micron lines and spaces for high performance applications. Reliability topics can also include board level reliability, ELK robustness, and Chip-Package-Interaction (CPI). Modeling and simulation of WLP and FO-WLP topics are also welcome.

Planned Sessions:

The track team is now planning four technical sessions for the 3-day Symposium.

Abstracts are being requested on the following topics:

Wafer-level Fan Out	WLCSP	Advanced Fan Out	Heterogeneous Integration
Panel-level Fan Out	MEMS & Sensors	Edge Protection	Carrier Technologies
Reliability & Test	ELK Robustness/CPI	Modeling & Simulation	Advanced WLP Materials
WLP and FO-WLP Equipment	New Panel Equipment for PLP		

Those wishing to present at IMAPS 2019 Boston must submit a 500+ word abstract electronically **no later than January 31, 2019**, using the on-line submittal form at www.imaps2019.org or www.imaps.org/abstracts.htm. Please contact Brian Schieman by email at bschieman@imaps.org if you have questions. **STUDENT AUTHORS:** upon abstract submission, please select "yes, I'm a full-time student" on the form and you will automatically be entered in the student competition.

If your abstract is selected, you will be asked to follow the speaker timeline: - Speaker Acceptance/Rejection (April 1); - First Paper to Peer Review (May 15); - Peer Review feedback to authors (July 1); - Final/corrected Papers (August 1); - Speaker must register before (August 15); - BIO due (September 15); Speaker Breakfast (morning of your session); and - Slides/Presentation ready (on/before September 30).

6 "Best of Track" Outstanding Papers - Six (6) Cash Awards

Six "Best of Track" Winners will then be reviewed for...

1 Best Paper of the Symposium - One (1) additional Cash Award for a "Best of Track" Winner

IMAPS Microelectronics Educational Foundation Student Paper Awards

The Foundation is offering CASH AWARDS to the best papers submitted and presented by students at IMAPS Symposium.